

semiconductor packaging news

EV Group and TOPPAN Photomask Join Forces – September 21, 2022

semiconductor packaging news

We search for industry news, so you don't need to.

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September 21, 2022

America's AI edge fading fast to China

A new report warns that the US may lose its technological edge over China by 2030 if it doesn't step up on strategic sectors critical to maintaining its advantages. The report titled "Mid-Decade Challenges to National Competitiveness," was released this month by the congressionally-mandated National Security Commission on Artificial Intelligence (NSCAI), an independent commission ...

Asia Times



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YES systems offer proven & reliable technology for thermal processing, wet processing, plasma etching & monolayer coating. Configurations from tabletop lab/R&D systems to HVM production.

Yield Engineering Systems



Do thin wafers have you frazzled?

Our new ADJUST-A-VAC allows you to reduce the vacuum pressure from just below atmospheric pressure to up to ten inches of mercury. A LED bar display shows the vacuum level.

Virtual Industries, Inc.



10 Questions: Handel Jones

Handel Jones, CEO of International Business Strategies and author of a new book, "When AI Rules The World," sat down with Semiconductor Engineering to talk about ...

Semiconductor Engineering

Empowering RF Front End Cellular Innovations with DSMBGA

With the introduction of 5G, cellular frequency bands have increased considerably, requiring innovative solutions for the packaging of RF front-end modules for smartphones ...

Technical Paper

Samsung's ups and downs (4): The manufacturing capability of Samsung's foundry biz

In 2020, Samsung Electronics had a monthly capacity of 260,000 wafers for its 8-inch and 12-inch fabrication each, which increased to 265,000 and 325,000 respectively ...

Digitimes

Technical Papers

- [Effects of Long-Term Storage on Mechanical and Electrical Integrity](#)
- [The Great Debate: Ball Bonding vs Wedge Bonding](#)
- [Chip-Last HDFO Interposer-PoP](#)
- [Air Gap, Buried Layer and Micro-Channel Measurement](#)
- [Essential Practices for Gold Mitigation of Electronic Components](#)
- [The Journey to Full-Scale Semiconductor Packaging Manufacturing](#)
- [Dispositioning Hermetic Microelectronic Components With High Internal Moisture](#)

Amkor's System in Package (SiP) Solutions

Amkor's SiP technology is an ideal solution in markets that demand a smaller size with increased functionality. Learn more.

Amkor Technology, Inc.



Hybrid Bonding Platform Solution

The automated SUSS XBS300 Hybrid Bonding Platform allows for state-of-the-art hybrid bonding at the highest accuracy on 200 and 300mm substrates.

SUSS MicroTec



EZ-FLO High Precision Dispense Tips

Each needle is machined from solid stainless steel as opposed to rolled tubing. The resulting smoother internal profile enhances material flow and consistency. Learn more.

DL Technology



Today's Sponsor



Test Your Knowledge

What is known as the universal solvent?
See answer below.

The Gold Standard of Bond Testing

Royce Instruments has been designing and building bond test equipment for over 30 years. The line of bond test equipment offers unmatched precision & robust operation for all your needs.

Royce Instruments



Press Releases

EV Group and Toppan Photomask Join Forces

EV Group (EVG) and Toppan Photomask Co. Ltd. announced that they have entered into an agreement to jointly market nanoimprint lithography (NIL) as an enabling ...

EV Group

StratEdge Offers Assembly Services for Die Attachment on CMC Tabs

StratEdge Corporation announces its assembly services for attaching gallium nitride (GaN) and other high-frequency, high-power devices using gold-tin (AuSn) and gold-silicon ...

StratEdge Corporation

VCSEL industry: a US\$3.9 billion market driven by consumer and datacom applications

By 2022, the VCSEL market has almost doubled compared to 2018, reaching US\$840 million. Starting in 2023, datacom could regain its supremacy and dominate the VCSEL ...

Yole Développement

Die Attach for Road-Ready Reliability

Seems difficult, but this long-desired balance has been achieved. Non-electrically conductive + high thermal + good dispense performance = Auto 0-standard reliability. Learn more.

Henkel Corporation



[Local chip firms need more support](#)

The government should step up financial support for local semiconductor companies and equipment manufacturers to ensure that Taiwan can safeguard its position ...

Taipei Times

[Why Geofencing Will Enable L5](#)

What will it take for a car to be able to drive itself anywhere a human can? Ask autonomous vehicle experts this question and the answer invariably includes a discussion ...

Semiconductor Engineering

[Korea's exports of key memory chip plummet as demand chills](#)

South Korea's exports of its most lucrative memory chip fell by the most since 2019, indicating a deepening slump in technology demand central to global economic ...

Digitimes

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SIEMENS
Engineer a smarter future faster with an advanced 3D IC design flow
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[Chinese IC startups face uncertain outlook](#)

Macroeconomic factors and changing investment strategy have taken their bites on China's semiconductor startups. As *Financial Times* reported, weakening market ...

Digitimes

[Research Bits: Sept. 20](#)

Researchers from ETH Zurich, the University of Zurich, and Empa built a new memristor that can operate in multiple modes and could potentially be used to mimic neurons ...

Semiconductor Engineering

[Semiconductor probe card suppliers may see earnings erode in 2023](#)

Companies specializing in probe cards for wafer tests and load boards for final tests may see their profits erode in 2023 as chipmakers including foundry TSMC and fabless ...

Digitimes

NanoResolution MRS™ Sensor
3D High precision optical sensor for packaging inspection & metrology. Inspect shiny or mirror-like surfaces with sub-micrometer accuracy for features as small as 25µm.
Cyberoptics Corporation

Die-Module Attach for High Power Devices
High flexibility film and paste adhesives for large die and module attach. Outstanding thermal conductivity with low moisture absorption stress-free bonding.
AI Technology, Inc.

[TSMC inaugurates water recycling plant in southern Taiwan](#)

Taiwan Semiconductor Manufacturing Co. (TSMC), the world's largest contract chipmaker, inaugurated a water recycling plant in the Tainan section of the Southern Taiwan ...

Focus Taiwan

X-ray inspection in SMT, semiconductors and labs

Heraeus Electronics
Advanced Assembly Materials ENABLING MINITURIZATION of Mini and MicroLED

Is IPA the best choice?
KYZEN offers safe, affordable

Quote of the Day

The right to be heard does not automatically include the right to be taken seriously."

Hubert Humphrey

Ultrasonic/Thermosonic Bonding Paper

Ultrasonic power is introduced during thermocompression bonding to perform die bonding at low temperature & pressure. Paper identifies processes to improve thermosonic bonding. Read more.
TRESKY Automation



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Boost SPI yields with SiPaste® C201HF. Formulated for fine feature printing, it combines cleanability in water-based solutions with excellent transfer efficiency.
Indium Corporation



What Year Was It?

[Benedict Arnold Commits Treason](#)

During the American Revolution, American General Benedict Arnold meets with British Major John Andre to discuss handing over West Point to the British, in return for the promise of a large sum of money and a high position in the British army.



[The day was Sep 21. What year was it?](#)

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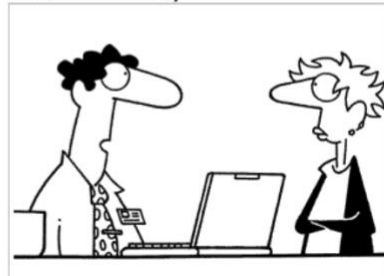


Diamond's thermal management properties enable higher performance

A collaboration between Univ. of Bristol and Element Six is accelerating diamond's path towards unlocking highly efficient thermal management solutions.
Element Six



Cartoon of the Day





Calendar

- [Sep 29, 2022: Overview of semiconductor manufacturing/Wakefield, MA](#)
- [Oct 3, 2022: Strategies to Revitalize the On-Shore Packaging and Assembly Defense Industrial Base](#)
- [Oct 4, 2022: 55th International Symposium on Microelectronics](#)
- [Oct 5, 2022: SEMICON China 2022](#)

NanoResolution MRS™ Sensor

3D High precision optical sensor for packaging inspection & metrology. Inspect shiny or mirror-like surfaces with sub-micrometer accuracy for features as small as 25µm.
Cyberoptics Corporation



Die-Module Attach for High Power Devices

High flexibility film and paste adhesives for large die and module attach. Outstanding thermal conductivity with low moisture absorption stress-free bonding.
AI Technology, Inc.



"What software would you recommend to give my presentation so much flash and sizzle that nobody notices that I have nothing to say?"
Copyright © Randy Glasbergen

92 Repair/Rework Guides Illustrated and Online

This free online guidebook, packed with detailed illustrations, will be helpful to anyone who needs to repair or rework circuit board assemblies.
Circuit Technology Center



Test Your Knowledge Answer

What is known as the universal solvent?
Answer: Water because it dissolves more substances than any other liquid.

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